

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Gang Chen</td> <td>07/04/2013</td> </tr> <tr> <td>Chunbo Liu</td> <td>07/08/2013</td> </tr> <tr> <td>Gabor Reizik</td> <td>07/08/2013</td> </tr> </tbody> </table>		Name	Execution Date	Gang Chen	07/04/2013	Chunbo Liu	07/08/2013	Gabor Reizik	07/08/2013
Name	Execution Date								
Gang Chen	07/04/2013								
Chunbo Liu	07/08/2013								
Gabor Reizik	07/08/2013								
RECEIVING PARTY DATA									
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC								
Street Address:	5005 E. MCDOWELL ROAD								
City:	Phoenix								
State/Country:	ARIZONA								
Postal Code:	85008								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13937943</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13937943				
Property Type	Number								
Application Number:	13937943								
CORRESPONDENCE DATA									
Fax Number:	6022443169								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	602-244-6648								
Email:	PATENTS@ONSEMI.COM								
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC								
Address Line 1:	5005 E. MCDOWELL ROAD								
Address Line 2:	Maildrop A700								
Address Line 4:	PHOENIX, ARIZONA 85008								
ATTORNEY DOCKET NUMBER:	ONS01534								
NAME OF SUBMITTER:	Lydia McNamara								
Signature:	/Lydia McNamara/								

Date:

07/09/2013

Total Attachments: 4

source=ONS01534_Assignment#page1.tif

source=ONS01534_Assignment#page2.tif

source=ONS01534_Assignment#page3.tif

source=ONS01534_Assignment#page4.tif

ASSIGNMENT & AGREEMENT

ONS01534

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

Name	of (City/State/Country)
Gang Chen	Taipo, N.T., Hong Kong
Chunbo Liu	San Jose, California, USA
Gabor Reizik	Dublin, California, USA

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

RIPPLE SUPPRESSOR CIRCUIT AND METHOD THEREFOR

Attorney Docket No. ON501534

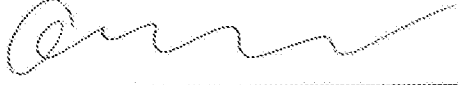
described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

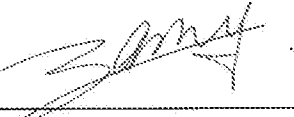
We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

By (Inventor signature): 
Gang Chen

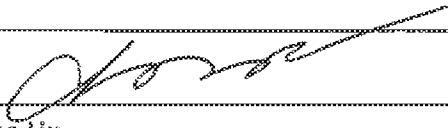
Witnessed by (Witness signature): 

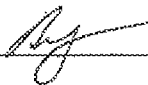
Printed name of Witness: YANG FENG

Signed and Witnessed on (date): July 4, 2013

ASSIGNMENT & AGREEMENT


ONS01534

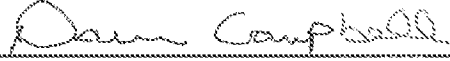
By (Inventor signature): 
Chunbo Liu

Witnessed by (Witness signature): 

Printed name of Witness: TONY WONG

Signed and Witnessed on (date): 7/8/2013

By (inventor signature): 
Gabor Reizik

Witnessed by (Witness signature): 

Printed name of Witness: Dawn Campbell

Signed and Witnessed on (date): July 8th, 2013